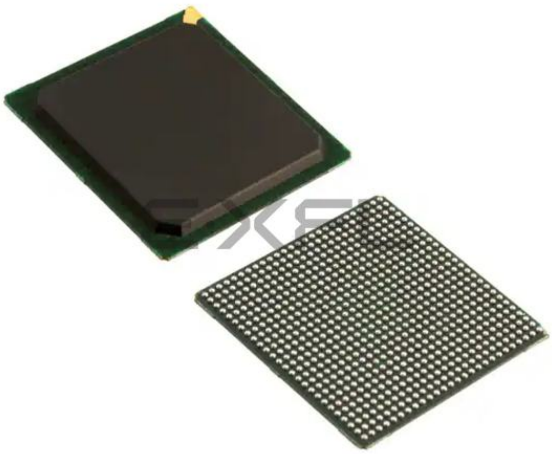

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	18144
Number of Logic Elements/Cells	-
Total RAM Bits	165888
Number of I/O	418
Number of Gates	1000000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 85°C (TA)
Package / Case	676-BGA
Supplier Device Package	676-FBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/ax1000-2fg676i

Up to four individual signals can be brought out to dedicated probe pins (PRA/B/C/D) on the device. The probe circuitry is accessed and controlled via Silicon Explorer II, Microsemi's integrated verification and logic analysis tool that attaches to the serial port of a PC and communicates with the FPGA via the JTAG port (See "Silicon Explorer II Probe Interface" on page 2-109).

Summary

Microsemi’s Axcelerator family of FPGAs extends the successful SX-A architecture, adding embedded RAM/FIFOs, PLLs, and high-speed I/Os. With the support of a suite of robust software tools, design engineers can incorporate high gate counts and fixed pins into an Axcelerator design yet still achieve high performance and efficient device utilization.

Related Documents

Application Notes

Simultaneous Switching Noise and Signal Integrity

http://www.microsemi.com/soc/documents/SSN_AN.pdf

Axcelerator Family PLL and Clock Management

http://www.microsemi.com/soc/documents/AX_PLL_AN.pdf

Implementation of Security in Actel Antifuse FPGAs

http://www.microsemi.com/soc/documents/Antifuse_Security_AN.pdf

User’s Guides and Manuals

Antifuse Macro Library Guide

http://www.microsemi.com/soc/documents/libguide_UG.pdf

SmartGen, FlashROM, Analog System Builder, and Flash Memory System Builder

http://www.microsemi.com/soc/documents/genguide_ug.pdf

Silicon Sculptor II User’s Guide

http://www.microsemi.com/soc/documents/silisculptII_sculpt3_ug.pdf

White Paper

Design Security in Nonvolatile Flash and Antifuse FPGAs

http://www.microsemi.com/soc/documents/DesignSecurity_WP.pdf

Understanding Actel Antifuse Device Security

http://www.microsemi.com/soc/documents/DesignSecurity_WP.pdf

Miscellaneous

Libero IDE flow diagram

http://www.microsemi.com/soc/products/tools/libero/flow.html

Poutputs = PI/O * po * Fpo

C_{load} = the output load (technology dependent)
VCCI = the output voltage (technology dependent)
po = the number of outputs
F_{po} = the average output frequency

Pmemory = P11 * Nblock * FRCLK + P12 * Nblock * FWCLK

N_{block} = the number of RAM/FIFO blocks (1 block = 4k)
F_{RCLK} = the read-clock frequency of the memory
F_{WCLK} = the write-clock frequency of the memory

PPLL = P13 * FCLK

F_{RefCLK} = the clock frequency of the clock input of the PLL
F_{CLK} = the clock frequency of the first clock output of the PLL

Power Estimation Example

This example employs an AX1000 shift-register design with 1,080 R-cells, one C-cell, one reset input, and one LVTTL 12 mA output, with high slew.

This design uses one HCLK at 100 MHz.

ms = 1,080 (in a shift register - 100% of R-cells are toggling at each clock cycle)
Fs = 100 MHz
s = 1080
=> P_{HCLK} = (P1 + P2 * s + P3 * sqrt[s]) * Fs = 79 mW
and Fs = 100 MHz
=> $P_{R\text{-}cells}$ = P7 * ms * Fs = 173 mW
mc = 1 (1 C-cell in this shift-register)
and Fs = 100 MHz
=> $P_{C\text{-}cells}$ = P8 * mc * Fs = 0.14 mW
F_{pi} ~ 0 MHz
and pi= 1 (1 reset input => this is why F_{pi}=0)
=> P_{inputs} = P9 * pi * F_{pi} = 0 mW
F_{po} = 50 MHz
and po = 1
=> $P_{outputs}$ = $P_{I/O}$ * po * F_{po}= 27.10 mW
No RAM/FIFO in this shift-register
=> P_{memory} = 0 mW
No PLL in this shift-register
=> P_{PLL} = 0 mW
$P_{ac} = P_{HCLK} + P_{CLK} + P_{R\text{-}cells} + P_{C\text{-}cells} + P_{inputs} + P_{outputs} + P_{memory} + P_{PLL}$ = 276 mW
P_{dc} = 7.5mA * 1.5V = 11.25 mW
$P_{total} = P_{dc} + P_{ac}$ = 11.25 mW + 276mW = 290.30 mW

Using the Differential I/O Standards

Differential I/O macros should be instantiated in the netlist. The settings for these I/O standards cannot be changed inside Designer. Note that there are no tristated or bidirectional I/O buffers for differential standards.

Using the Voltage-Referenced I/O Standards

Using these I/O standards is similar to that of single-ended I/O standards. Their settings can be changed in Designer.

Using DDR (Double Data Rate)

In Double Data Rate mode, new data is present on every transition of the clock signal. Clock and data lines have identical bandwidth and signal integrity requirements, making it very efficient for implementing very high-speed systems.

To implement a DDR, users need to:

1. Instantiate an input buffer (with the required I/O standard)
2. Instantiate the DDR_REG macro (Figure 2-6)
3. Connect the output from the Input buffer to the input of the DDR macro

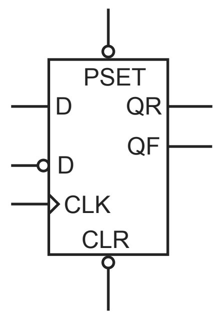


Figure 2-6 • **DDR Register**

Macros for Specific I/O Standards

There are different macro types for any I/O standard or feature that determine the required VCCI and VREF voltages for an I/O. The generic buffer macros require the LVTTL standard with slow slew rate and 24 mA-drive strength. LVTTL can support high slew rate but this should only be used for critical signals.

Most of the macro symbols represent variations of the six generic symbol types:

- CLKBUF: Clock Buffer
- HCLKBUF: Hardwired Clock Buffer
- INBUF: Input Buffer
- OUTBUF: Output Buffer
- TRIBUF: Tristate Buffer
- BIBUF: Bidirectional Buffer

Other macros include the following:

- Differential I/O standard macros: The LVDS and LVPECL macros either have a pair of differential inputs (e.g. INBUF_LVDS) or a pair of differential outputs (e.g. OUTBUF_LVPECL).
- Pull-up and pull-down variations of the INBUF, BIBUF, and TRIBUF macros. These are available only with TTL and LVCMOS thresholds. They can be used to model the behavior of the pull-up and pull-down resistors available in the architecture. Whenever an input pin is left unconnected, the output pin will either go high or low rather than unknown. This allows users to leave inputs unconnected without having the negative effect on simulation of propagating unknowns.
- DDR_REG macro. It can be connected to any I/O standard input buffers (i.e. INBUF) to implement a double data rate register. Designer software will map it to the I/O module in the same way it maps the other registers to the I/O module.

3.3 V LVTTL

Low-Voltage Transistor-Transistor Logic is a general purpose standard (EIA/JESD) for 3.3 V applications. It uses an LVTTL input buffer and push-pull output buffer.

***Table 2-20* • DC Input and Output Levels**

VIL		VIH		VOL	VOH	IOL	IOH
Min., V	**Max., V**	**Min., V**	**Max., V**	**Max., V**	**Min., V**	**mA**	**mA**
–0.3	0.8	2.0	3.6	0.4	2.4	24	–24

AC Loadings

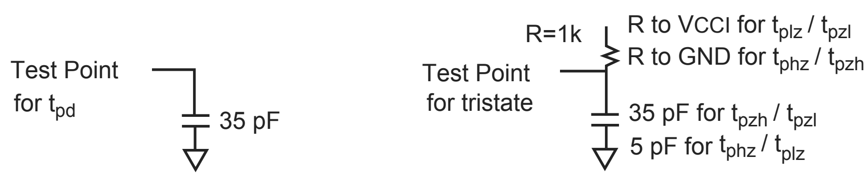


***Figure 2-15* • AC Test Loads**

***Table 2-21* • AC Waveforms, Measuring Points, and Capacitive Load**

Input Low (V)	Input High (V)	Measuring Point* (V)	VREF (typ) (V)	C_{load} (pF)
0	3.0	1.40	N/A	35

*Note: * Measuring Point = VTRIP*

Timing Characteristics

Table 2-25 • 2.5V LVCMOS I/O Module
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 2.3 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
LVCMOS25 I/O Module Timing								
t_{DP}	Input Buffer		1.95		2.22		2.61	ns
t_{PY}	Output Buffer		3.29		3.74		4.40	ns
t_{ENZL}	Enable to Pad Delay through the Output Buffer—Z to Low		2.48		2.50		2.51	ns
t_{ENZH}	Enable to Pad Delay through the Output Buffer—Z to High		2.48		2.50		2.51	ns
t_{ENLZ}	Enable to Pad Delay through the Output Buffer—Low to Z		5.74		6.54		7.69	ns
t_{ENHZ}	Enable to Pad Delay through the Output Buffer—High to Z		6.60		7.51		8.83	ns
t_{IOCLKQ}	Sequential Clock-to-Q for the I/O Input Register		0.67		0.77		0.90	ns
t_{IOCLKY}	Clock-to-output Y for the I/O Output Register and the I/O Enable Register		0.67		0.77		0.90	ns
t_{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t_{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t_{HD}	Data Input Hold		0.00		0.00		0.00	ns
t_{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t_{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t_{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t_{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t_{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t_{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t_{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

Table 2-36 **• 3.3 V PCI-X I/O Module**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
3.3 V PCI-X Output Module Timing								
t_{DP}	Input Buffer		1.57		1.79		2.10	ns
t_{PY}	Output Buffer		2.10		2.40		2.82	ns
t_{ENZL}	Enable to Pad Delay through the Output Buffer—Z to Low		1.61		1.62		1.63	ns
t_{ENZH}	Enable to Pad Delay through the Output Buffer—Z to High		1.59		1.60		1.61	ns
t_{ENLZ}	Enable to Pad Delay through the Output Buffer—Low to Z		2.65		3.02		3.55	ns
t_{ENHZ}	Enable to Pad Delay through the Output Buffer—High to Z		3.11		3.55		4.17	ns
t_{IOCLKQ}	Sequential Clock-to-Q for the I/O Input Register		0.67		0.77		0.90	ns
t_{IOCLKY}	Clock-to-output Y for the I/O Output Register and the I/O Enable Register		0.67		0.77		0.90	ns
t_{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t_{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t_{HD}	Data Input Hold		0.00		0.00		0.00	ns
t_{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t_{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t_{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t_{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t_{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t_{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t_{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

Class II

Table 2-47 • DC Input and Output Levels

VIL		VIH		VOL	VOH	IOL	IOH
Min., V	Max., V	Min., V	Max., V	Max., V	Min,. V	mA	mA
-0.3	VREF – 0.2	VREF + 0.2	3.6	VREF – 0.8	VREF + 0.8	15.2	-15.2

AC Loadings

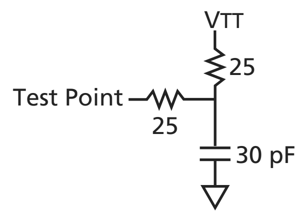


Figure 2-22 • AC Test Loads

Table 2-48 • AC Waveforms, Measuring Points, and Capacitive Loads

Input Low (V)	Input High (V)	Measuring Point* (V)	VREF (typ) (V)	C_{load} (pF)
VREF – 0.75	VREF + 0.75	VREF	1.25	30

Note: * Measuring Point = V_{trip}

Timing Characteristics

Table 2-49 • 2.5 V SSTL2 Class II I/O Module
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 2.3 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	Units
2.5 V SSTL2 Class II I/O Module Timing								
t_{DP}	Input Buffer		1.89		2.16		2.53	ns
t_{PY}	Output Buffer		2.39		2.72		3.20	ns
t_{ICLKQ}	Clock-to-Q for the I/O input register		0.67		0.77		0.90	ns
t_{OCLKQ}	Clock-to-Q for the I/O output register and the I/O enable register		0.67		0.77		0.90	ns
t_{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t_{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t_{HD}	Data Input Hold		0.00		0.00		0.00	ns
t_{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t_{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t_{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t_{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t_{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t_{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t_{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

Buffer Module

Introduction

An additional resource inside each SuperCluster is the Buffer (B) module (Figure 1-4 on page 1-3). When a fanout constraint is applied to a design, the synthesis tool inserts buffers as needed. The buffer module has been added to the AX architecture to avoid logic duplication resulting from the hard fanout constraints. The router utilizes this logic resource to save area and reduce loading and delays on medium-to-high-fanout nets.

Timing Models and Waveforms

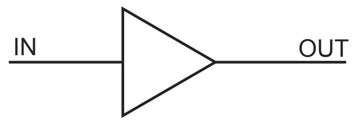


Figure 2-33 • **Buffer Module Timing Model**

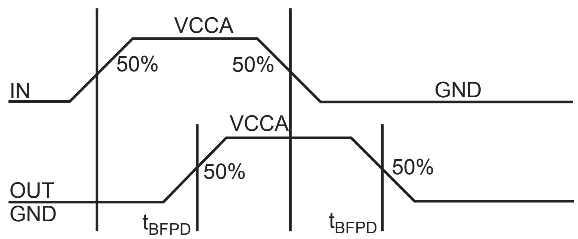


Figure 2-34 • **Buffer Module Waveform**

Timing Characteristics

***Table 2-64* • Buffer Module**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
Buffer Module Propagation Delays								
t_{BFPD}	Any input to output Y		0.12		0.14		0.16	ns

single-ended, or voltage-referenced standard. The [H]CLKxN pad can only be used as a differential pair with [H]CLKxP.

The block marked "/i Delay Match" is a fixed delay equal to that of the i divider. The "/j Delay Match" block has the same function as its j divider counterpart.

Functional Description

Figure 2-48 on page 2-75 illustrates a block diagram of the PLL. The PLL contains two dividers, i and j, that allow frequency scaling of the clock signal:

- The i divider in the feedback path allows multiplication of the input clock by integer factors ranging from 1 to 64, and the resultant frequency is available at the output of the PLL block.
- The j divider divides the PLL output by integer factors ranging from 1 to 64, and the divided clock is available at CLK1.
- The two dividers together can implement any combination of multiplication and division up to a maximum frequency of 1 GHz on CLK1. Both the CLK1 and CLK2 outputs have a fixed 50/50 duty cycle.
- The output frequencies of the two clocks are given by the following formulas (f_{REF} is the reference clock frequency):

$$f_{CLK1} = f_{REF} * (DividerI) / (DividerJ)$$

EQ 4

$$f_{CLK2} = f_{REF} * (DividerI)$$

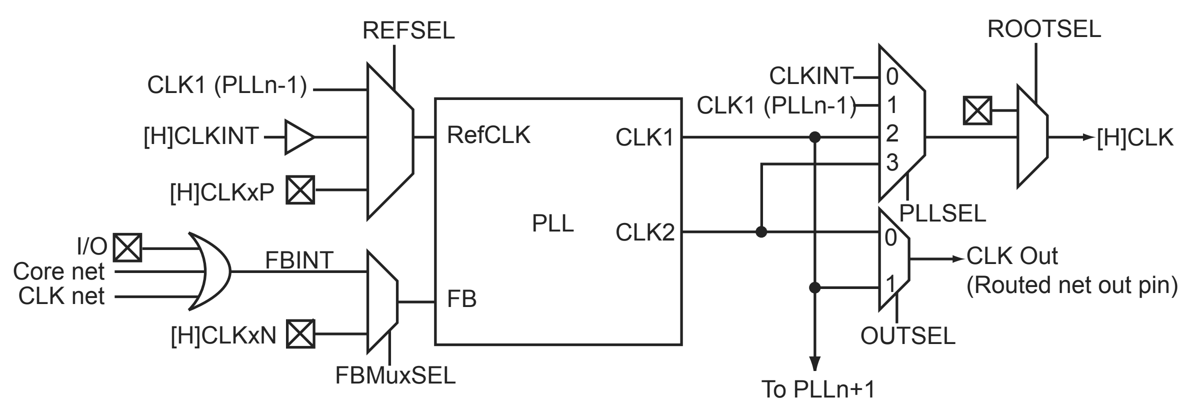
EQ 5

- CLK2 provides the PLL output directly—without division

The input and output frequency ranges are selected by LowFreq and Osc(2:0), respectively. These functions and their possible values are detailed in Table 2-80 on page 2-77.

The delay lines shown in Figure 2-48 on page 2-75 are programmable. The feedback clock path can be delayed (using the five DelayLine bits) relative to the reference clock (or vice versa) by up to 3.75 ns in increments of 250 ps. Table 2-80 on page 2-77 describes the usage of these bits. The delay increments are independent of frequency, so this results in phase changes that vary with frequency. The delay value is highly dependent on V_{CC} and the speed grade.

Figure 2-49 is a logical diagram of the various control signals to the PLL and shows how the PLL interfaces with the global and routing networks of the FPGA. Note that not all signals are user-accessible. These non-user-accessible signals are used by the place-and-route tool to control the configuration of the PLL. The user gains access to these control signals either based upon the connections built in the user's design or through the special macros (Table 2-84 on page 2-81) inserted into the design. For example, connecting the macro PLLOUT to CLK2 will control the OUTSEL signal.



Note: Not all signals are available to the user.

Figure 2-49 • **PLL Logical Interface**

Table 2-91 • Four RAM Blocks Cascaded
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
Write Mode								
t_{WDASU}	Write Data Setup vs. WCLK		2.37		2.70		3.17	ns
t_{WDAHD}	Write Data Hold vs. WCLK		0.00		0.00		0.00	ns
t_{WADSU}	Write Address Setup vs. WCLK		2.37		2.70		3.17	ns
t_{WADHD}	Write Address Hold vs. WCLK		0.00		0.00		0.00	ns
t_{WENSU}	Write Enable Setup vs. WCLK		2.37		2.70		3.17	ns
t_{WENHD}	Write Enable Hold vs. WCLK		0.00		0.00		0.00	ns
t_{WCKH}	WCLK Minimum High Pulse Width	0.75		0.75		0.75		ns
t_{WCLK}	WCLK Minimum Low Pulse Width	2.51		2.51		2.51		ns
t_{WCKP}	WCLK Minimum Period	3.26		3.26		3.26		ns
Read Mode								
t_{RADSU}	Read Address Setup vs. RCLK		3.08		3.51		4.13	ns
t_{RADHD}	Read Address Hold vs. RCLK		0.00		0.00		0.00	ns
t_{RENSU}	Read Enable Setup vs. RCLK		3.08		3.51		4.13	ns
t_{RENHD}	Read Enable Hold vs. RCLK		0.00		0.00		0.00	ns
$t_{RCK2RD1}$	RCLK-To-OUT (Pipelined)		2.36		2.69		3.16	ns
$t_{RCK2RD2}$	RCLK-To-OUT (Non-Pipelined)		2.83		3.23		3.79	ns
t_{RCLKH}	RCLK Minimum High Pulse Width	0.73		0.73		0.73		ns
t_{RCLKL}	RCLK Minimum Low Pulse Width	2.96		2.96		2.96		ns
t_{RCKP}	RCLK Minimum Period	3.69		3.69		3.69		ns

Note: Timing data for these four cascaded RAM blocks uses a depth of 16,384. For all other combinations, use Microsemi's timing software.

Table 2-92 • Eight RAM Blocks Cascaded
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
Write Mode								
t_{WDASU}	Write Data Setup vs. WCLK		5.78		6.58		7.74	ns
t_{WDAHD}	Write Data Hold vs. WCLK		0.00		0.00		0.00	ns
t_{WADSU}	Write Address Setup vs. WCLK		5.78		6.58		7.74	ns
t_{WADHD}	Write Address Hold vs. WCLK		0.00		0.00		0.00	ns
t_{WENSU}	Write Enable Setup vs. WCLK		5.78		6.58		7.74	ns
t_{WENHD}	Write Enable Hold vs. WCLK		0.00		0.00		0.00	ns
t_{WCKH}	WCLK Minimum High Pulse Width	0.75		0.75		0.75		ns
t_{WCLK}	WCLK Minimum Low Pulse Width	5.13		5.13		5.13		ns
t_{WCKP}	WCLK Minimum Period	5.88		5.88		5.88		ns
Read Mode								
t_{RADSU}	Read Address Setup vs. RCLK		6.75		7.69		9.04	ns
t_{RADHD}	Read Address Hold vs. RCLK		0.00		0.00		0.00	ns
t_{RENSU}	Read Enable Setup vs. RCLK		6.75		7.69		9.04	ns
t_{RENHD}	Read Enable Hold vs. RCLK		0.00		0.00		0.00	ns
$t_{RCK2RD1}$	RCLK-To-OUT (Pipelined)		3.39		3.86		4.54	ns
$t_{RCK2RD2}$	RCLK-To-OUT (Non-Pipelined)		4.93		5.62		6.61	ns
t_{RCLKH}	RCLK Minimum High Pulse Width	0.73		0.73		0.73		ns
t_{RCLKL}	RCLK Minimum Low Pulse Width	5.77		5.77		5.77		ns
t_{RCKP}	RCLK Minimum Period	6.50		6.50		6.50		ns

Note: Timing data for these eight cascaded RAM blocks uses a depth of 32,768. For all other combinations, use Microsemi's timing software.

Glitch Elimination

An analog filter is added to each FIFO controller to guarantee glitch-free FIFO-flag logic.

Overflow and Underflow Control

The counter MSB keeps track of the difference between the read address (RA) and the write address (WA). The EMPTY flag is set when the read and write addresses are equal. To prevent underflow, the write address is double-sampled by the read clock prior to comparison with the read address (part A in Figure 2-64). To prevent overflow, the read address is double-sampled by the write clock prior to comparison to the write address (part B in Figure 2-64).

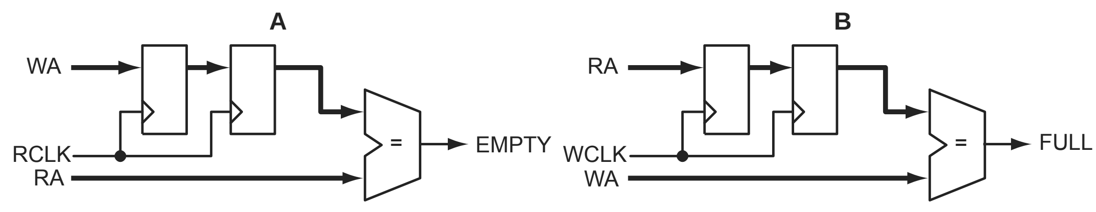


Figure 2-64 • **Overflow and Underflow Control**

FIFO Configurations

Unlike the RAM, the FIFO's write width and read width cannot be specified independently. For the FIFO, the write and read widths must be the same. The WIDTH pins are used to specify one of six allowable word widths, as shown in Table 2-96.

Table 2-96 **• FIFO Width Configurations**

WIDTH(2:0)	W x D
000	1 x 4k
001	2 x 2k
010	4 x 1k
011	9 x 512
100	18 x 256
101	36 x 128
11x	reserved

The DEPTH pins allow RAM cells to be cascaded to create larger FIFOs. The four pins allow depths of 2, 4, 8, and 16 to be specified. Table 2-86 on page 2-87 describes the FIFO depth options for various data width and memory blocks.

Interface

Figure 2-65 on page 2-99 shows a logic block diagram of the Axcelerator FIFO module.

Cascading FIFO Blocks

FIFO blocks can be cascaded to create deeper FIFO functions. When building larger FIFO blocks, if the word width can be fractured in a multi-bit FIFO, the fractured word configuration is recommended over a cascaded configuration. For example, 256x36 can be configured as two blocks of 256x18. This should be taken into account when building the FIFO blocks manually. However, when using SmartGen, the user only needs to specify the depth and width of the necessary FIFO blocks. SmartGen automatically configures these blocks to optimize performance.

BG729	
AX1000 Function	Pin Number
IO218PB6F20	V2
IO219NB6F20	T1
IO219PB6F20	U1
IO220NB6F20	R5
IO220PB6F20	R6
IO221NB6F20	T3
IO221PB6F20	T4
IO222NB6F20	R2
IO222PB6F20	T2
IO223NB6F20	P8
IO223PB6F20	P9
IO224NB6F20	R3
IO224PB6F20	R4
Bank 7	
IO225NB7F21	P1
IO225PB7F21	R1
IO226NB7F21	P3
IO226PB7F21	P2
IO227NB7F21	N7
IO227PB7F21	P7
IO228NB7F21	P5
IO228PB7F21	P4
IO229NB7F21	N2
IO229PB7F21	N1
IO230NB7F21	N6
IO230PB7F21	P6
IO231NB7F21	N9
IO231PB7F21	N8
IO232NB7F21	N4
IO232PB7F21	N3
IO233NB7F21	M2
IO233PB7F21	M1
IO234NB7F21	M4
IO234PB7F21	M3
IO235NB7F21	M5
IO235PB7F21	N5
IO236NB7F22	L2

BG729	
AX1000 Function	Pin Number
IO236PB7F22	L1
IO237NB7F22	L4
IO237PB7F22	L3
IO238NB7F22	L6
IO238PB7F22	M6
IO239NB7F22	M8
IO239PB7F22	M7
IO240NB7F22	K2
IO240PB7F22	K1
IO241NB7F22	K4
IO241PB7F22	K3
IO242NB7F22	K5
IO242PB7F22	L5
IO243NB7F22	J2
IO243PB7F22	J1
IO244NB7F22	J4
IO244PB7F22	J3
IO245NB7F22	H2
IO245PB7F22	H1
IO246NB7F22	H4
IO246PB7F22	H3
IO247NB7F23	L8
IO247PB7F23	L7
IO248NB7F23	J6
IO248PB7F23	K6
IO249NB7F23	H5
IO249PB7F23	J5
IO250NB7F23	G2
IO250PB7F23	G1
IO251NB7F23	K8
IO251PB7F23	K7
IO252NB7F23	G4
IO252PB7F23	G3
IO253NB7F23	F2
IO253PB7F23	F1
IO254NB7F23	G6
IO254PB7F23	H6

BG729	
AX1000 Function	Pin Number
IO255NB7F23	F5
IO255PB7F23	G5
IO256NB7F23	F3
IO256PB7F23	F4
IO257NB7F23	H7
IO257PB7F23	J7
Dedicated I/O	
GND	A1
GND	A2
GND	A25
GND	A26
GND	A27
GND	A3
GND	AC24
GND	AE1
GND	AE2
GND	AE25
GND	AE26
GND	AE27
GND	AE3
GND	AE5
GND	AF1
GND	AF2
GND	AF25
GND	AF26
GND	AF27
GND	AF3
GND	AG1
GND	AG2
GND	AG25
GND	AG26
GND	AG27
GND	AG3
GND	B1
GND	B2
GND	B25
GND	B26

FG324	
AX125 Function	Pin Number
IO50NB4F4/CLKFN	U9
IO50PB4F4/CLKFP	U10
Bank 5	
IO51NB5F5/CLKGN	R8
IO51PB5F5/CLKGP	R9
IO52NB5F5/CLKHN	T7
IO52PB5F5/CLKHP	T8
IO53NB5F5	U6
IO53PB5F5	U7
IO54NB5F5	V8
IO54PB5F5	V9
IO55NB5F5	V6
IO55PB5F5	V7
IO56NB5F5	U4
IO56PB5F5	U5
IO57NB5F5	T4
IO57PB5F5	T5
IO58NB5F5	V4
IO58PB5F5	V5
IO59NB5F5	V2
IO59PB5F5	V3
Bank 6	
IO60NB6F6	P5
IO60PB6F6	P6
IO61NB6F6	T2
IO61PB6F6	U3
IO62NB6F6	T1
IO62PB6F6	U1
IO63NB6F6	P1
IO63PB6F6	R1
IO64NB6F6	R3
IO64PB6F6	P3
IO65NB6F6	P2
IO65PB6F6	R2
IO66NB6F6	M3

FG324	
AX125 Function	Pin Number
IO66PB6F6	N3
IO67NB6F6	M2
IO67PB6F6	N2
IO68NB6F6	M1
IO68PB6F6	N1
IO69NB6F6	K4
IO69PB6F6	L4
IO70NB6F6	K1
IO70PB6F6	L1
IO71NB6F6	K3
IO71PB6F6	L3
Bank 7	
IO72NB7F7	H4
IO72PB7F7	J4
IO73NB7F7	K2
IO73PB7F7	L2
IO74NB7F7	H2
IO74PB7F7	H1
IO75NB7F7	H3
IO75PB7F7	J3
IO76NB7F7	F2
IO76PB7F7	G2
IO77NB7F7	F1
IO77PB7F7	G1
IO78NB7F7	D2
IO78PB7F7	E2
IO79NB7F7	F3
IO79PB7F7	G3
IO80NB7F7	E3
IO80PB7F7	E4
IO81NB7F7	D1
IO81PB7F7	E1
IO82NB7F7	D3
IO82PB7F7	C2
IO83NB7F7	B1

FG324	
AX125 Function	Pin Number
IO83PB7F7	C1
Dedicated I/O	
VCCDA	F5
GND	A1
GND	A18
GND	B17
GND	B2
GND	C16
GND	C3
GND	E16
GND	F13
GND	F6
GND	G12
GND	G7
GND	H10
GND	H11
GND	H8
GND	H9
GND	J10
GND	J11
GND	J8
GND	J9
GND	K10
GND	K11
GND	K8
GND	K9
GND	L10
GND	L11
GND	L8
GND	L9
GND	M12
GND	M7
GND	N13
GND	N6
GND	R14

FG484	
AX1000 Function	**Pin Number**
IO167PB5F15	AA12
IO169NB5F15	AA9
IO169PB5F15	AA10
IO170NB5F15	AB9
IO170PB5F15	AB10
IO171NB5F16	W8
IO171PB5F16	W9
IO172NB5F16	Y8
IO172PB5F16	Y9
IO173NB5F16	U8
IO173PB5F16	U9
IO174NB5F16	AA7
IO174PB5F16	AA8
IO175NB5F16	AB5
IO175PB5F16	AB6
IO176NB5F16	AA5
IO176PB5F16	AA6
IO177NB5F16	AA4
IO177PB5F16	AB4
IO178NB5F16	Y6
IO178PB5F16	Y7
IO179NB5F16	T7
IO179PB5F16	T8
IO180NB5F16	W6
IO180PB5F16	W7
IO181NB5F17	Y4
IO181PB5F17	Y5
IO184NB5F17	AB7
IO187NB5F17	V3
IO187PB5F17	W3
IO188NB5F17	V4
IO188PB5F17	W5
IO192NB5F17	V6
IO192PB5F17	V7
Bank 6	

FG484	
AX1000 Function	**Pin Number**
IO194NB6F18	V2
IO194PB6F18	W2
IO195NB6F18	U5
IO195PB6F18	T5
IO200NB6F18	T4
IO200PB6F18	U4
IO201NB6F18	P6
IO201PB6F18	R6
IO203NB6F19	U2
IO204NB6F19	T3
IO204PB6F19	U3
IO205NB6F19	P5
IO205PB6F19	R5
IO208NB6F19	V1
IO208PB6F19	W1
IO209NB6F19	P7
IO209PB6F19	R7
IO212NB6F19	P4
IO212PB6F19	R4
IO214NB6F20	P3
IO214PB6F20	R3
IO215NB6F20	M6
IO215PB6F20	N6
IO216NB6F20	R2
IO216PB6F20	T2
IO217NB6F20	T1
IO217PB6F20	U1
IO219NB6F20	M5
IO219PB6F20	N5
IO220NB6F20	P1
IO220PB6F20	R1
IO221NB6F20	N2
IO221PB6F20	P2
IO222NB6F20	M3
IO222PB6F20	N3

FG484	
AX1000 Function	**Pin Number**
IO223NB6F20	M7
IO223PB6F20	N7
IO224NB6F20	M4
IO224PB6F20	N4
Bank 7	
IO225NB7F21	M2
IO225PB7F21	N1
IO226NB7F21	K2
IO226PB7F21	K1
IO228NB7F21	L3
IO228PB7F21	L2
IO229NB7F21	K5
IO229PB7F21	L5
IO230NB7F21	H1
IO230PB7F21	J1
IO231NB7F21	H2
IO231PB7F21	J2
IO232NB7F21	K4
IO232PB7F21	K3
IO233NB7F21	K6
IO233PB7F21	L6
IO234NB7F21	F1
IO234PB7F21	G1
IO235NB7F21	F2
IO235PB7F21	G2
IO236NB7F22	H3
IO236PB7F22	J3
IO237NB7F22	K7
IO237PB7F22	L7
IO241NB7F22	H6
IO241PB7F22	J6
IO242NB7F22	H4
IO242PB7F22	J4
IO243NB7F22	H5
IO243PB7F22	J5

FG676	
AX500 Function	**Pin Number**
VCCIB3	T19
VCCIB3	U19
VCCIB3	U20
VCCIB3	V19
VCCIB3	V20
VCCIB3	W20
VCCIB4	W14
VCCIB4	W15
VCCIB4	W16
VCCIB4	W17
VCCIB4	W18
VCCIB4	Y17
VCCIB4	Y18
VCCIB4	Y19
VCCIB5	W10
VCCIB5	W11
VCCIB5	W12
VCCIB5	W13
VCCIB5	W9
VCCIB5	Y10
VCCIB5	Y8
VCCIB5	Y9
VCCIB6	P8
VCCIB6	R8
VCCIB6	T8
VCCIB6	U7
VCCIB6	U8
VCCIB6	V7
VCCIB6	V8
VCCIB6	W7
VCCIB7	H7
VCCIB7	J7
VCCIB7	J8
VCCIB7	K7
VCCIB7	K8

FG676	
AX500 Function	**Pin Number**
VCCIB7	L8
VCCIB7	M8
VCCIB7	N8
VCCPLA	E12
VCCPLB	F13
VCCPLC	E15
VCCPLD	G14
VCCPLE	AF15
VCCPLF	AA14
VCCPLG	AF12
VCCPLH	AB13
VCOMPLA	D12
VCOMPLB	G13
VCOMPLC	D15
VCOMPLD	F14
VCOMPLE	AD15
VCOMPLF	AB14
VCOMPLG	AD12
VCOMPLH	Y13
VPUMP	E22

PQ208	
AX250 Function	Pin Number
IO110PB7F7	19
IO112NB7F7	16
IO112PB7F7	17
IO117NB7F7	12
IO117PB7F7	13
IO119NB7F7	10
IO119PB7F7	11
IO121PB7F7	7
IO122NB7F7	5
IO122PB7F7	6
IO123NB7F7	3
IO123PB7F7	4
Dedicated I/O	
VCCDA	1
VCCDA	26
VCCDA	53
VCCDA	63
VCCDA	78
VCCDA	95
VCCDA	105
VCCDA	130
VCCDA	157
VCCDA	167
VCCDA	182
VCCDA	202
GND	104
GND	9
GND	15
GND	21
GND	32
GND	39
GND	46
GND	51
GND	59
GND	65
GND	69
GND	90

PQ208	
AX250 Function	Pin Number
GND	94
GND	99
GND	113
GND	119
GND	125
GND	136
GND	143
GND	150
GND	155
GND	164
GND	169
GND	173
GND	194
GND	196
GND	201
GND/LP	208
PRA	184
PRB	183
PRC	80
PRD	79
TCK	205
TDI	204
TDO	203
TMS	206
TRST	207
VCCA	2
VCCA	52
VCCA	156
VCCA	14
VCCA	38
VCCA	64
VCCA	93
VCCA	118
VCCA	142
VCCA	168
VCCA	195
VCCPLA	189

PQ208	
AX250 Function	Pin Number
VCCPLB	187
VCCPLC	178
VCCPLD	176
VCCPLE	85
VCCPLF	83
VCCPLG	74
VCCPLH	72
VCCIB0	193
VCCIB0	200
VCCIB1	163
VCCIB1	172
VCCIB2	135
VCCIB2	149
VCCIB3	112
VCCIB3	124
VCCIB4	89
VCCIB4	98
VCCIB5	58
VCCIB5	68
VCCIB6	31
VCCIB6	45
VCCIB7	8
VCCIB7	20
VCOMPLA	190
VCOMPLB	188
VCOMPLC	179
VCOMPLD	177
VCOMPLE	86
VCOMPLF	84
VCOMPLG	75
VCOMPLH	73
VPUMP	158

CG624	
AX2000 Function	Pin Number
VCCIB2	D23
VCCIB2	E22
VCCIB2	K17
VCCIB2	L17
VCCIB2	M16
VCCIB3	AA22
VCCIB3	AB23
VCCIB3	AC24
VCCIB3	AC25
VCCIB3	P16
VCCIB3	R17
VCCIB3	T17
VCCIB4	AB21
VCCIB4	AC22
VCCIB4	AD23
VCCIB4	AE23
VCCIB4	T14
VCCIB4	U15
VCCIB4	U16
VCCIB5	AB5
VCCIB5	AC4
VCCIB5	AD3
VCCIB5	AE3
VCCIB5	T12
VCCIB5	U10
VCCIB5	U11
VCCIB6	AA4
VCCIB6	AB3
VCCIB6	AC1
VCCIB6	AC2
VCCIB6	P10
VCCIB6	R9

*Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.*

CG624	
AX2000 Function	Pin Number
VCCIB6	T9
VCCIB7	C1
VCCIB7	C2
VCCIB7	D3
VCCIB7	E4
VCCIB7	K9
VCCIB7	L9
VCCIB7	M10
VCCPLA	E12
VCCPLB	J12
VCCPLC	E14
VCCPLD	H14
VCCPLE	Y14
VCCPLF	U14
VCCPLG	Y12
VCCPLH	U12
VCOMPLA	F12
VCOMPLB	H12
VCOMPLC	F14
VCOMPLD	J14
VCOMPLE	AA14
VCOMPLF	V14
VCOMPLG	AA12
VCOMPLH	V12
VPUMP	E20

*Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.*